

Based Material Line Up



S1190/S1190B

1. CORE (C-STAGE)

Thickness		ply-up	RC (%)	Dk				Df			
mm	mil			1 GHz	3 GHz	5 GHz	10 GHz	1 GHz	3 GHz	5 GHz	10 GHz
0.050	2.0	1*106	72	4.0	4.0	3.9	3.8	0.017	0.021	0.022	0.022
0.060	2.4	1*106	76	3.9	3.8	3.8	3.7	0.018	0.022	0.023	0.022
0.075	3.0	1*1080	64	4.2	4.2	4.2	4.1	0.016	0.019	0.020	0.020
0.086	3.4	1*1080	68	4.1	4.1	4.1	3.9	0.016	0.020	0.021	0.021
0.100	4.0	1*3313	56	4.5	4.5	4.5	4.4	0.014	0.018	0.018	0.018
0.110	4.3	1*2116	50	4.7	4.7	4.7	4.6	0.013	0.016	0.017	0.017
0.127	5.0	1*2116	56	4.5	4.5	4.5	4.4	0.014	0.018	0.018	0.018
0.150	6.0	2*1080	64	4.2	4.2	4.2	4.1	0.016	0.019	0.020	0.020
0.200	8.0	2*3313	56	4.5	4.5	4.5	4.4	0.014	0.018	0.018	0.018
0.254	10	2*2116	56	4.5	4.5	4.5	4.4	0.014	0.018	0.018	0.018
0.300	12	3*3313	56	4.5	4.5	4.5	4.4	0.014	0.018	0.018	0.018

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2. PREPREG (B-STAGE)

Glass style	RC (%)	Thickness		Dk				Df			
	Nominal	mm	mil	1GHz	3GHz	5GHz	10GHz	1 GHz	3 GHz	5 GHz	10 GHz
106	72	0.050	2.0	4.0	4.0	3.9	3.8	0.017	0.021	0.022	0.022
	76	0.060	2.4	3.9	3.8	3.8	3.7	0.018	0.022	0.023	0.022
1080	64	0.075	3.0	4.2	4.2	4.2	4.1	0.016	0.019	0.020	0.020
	68	0.086	3.4	4.1	4.1	4.1	3.9	0.016	0.020	0.021	0.021
3313	56	0.100	3.9	4.5	4.5	4.5	4.4	0.014	0.018	0.018	0.018
2116	50	0.110	4.3	4.7	4.7	4.7	4.6	0.013	0.016	0.017	0.017
	56	0.125	4.9	4.5	4.5	4.5	4.4	0.014	0.018	0.018	0.018

3. REMARK

- 1) Test by SPDR method
- 2) The data above show actual values and are not guaranteed.
- 3) Last update: July, 2018